Preliminary data sheet

1. General description

Planar passivated Silicon Controlled Rectifier (SCR) module in WeEnTOP-B for use in applications requiring high blocking voltage capability, high inrush current capability and high thermal cycling performance

2. Features and benefits

- · Planar passivated thyristor chips for voltage ruggedness and reliability
- Top-side cooling
- Compact design
- One screw mounting
- Heat transfer and isolation through direct copper bonded aluminum oxide ceramic (DBC)
- · Package is RoHS compliant

3. Applications

- · Soft starters
- UPS
- · Temperature control
- Lighting control
- AC power control

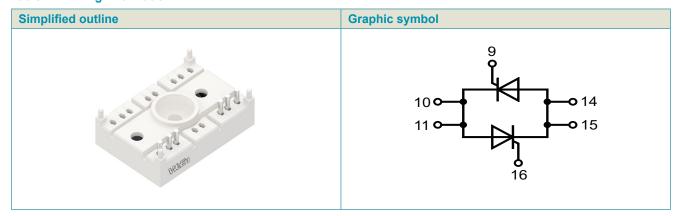
4. Quick reference data

Table 1. Quick reference data

Symbol	Parameter	Conditions	Notes		Values		Unit	
Absolute maximum rating								
V_{DRM}	repetitive peak forward voltage				1600		V	
V_{RRM}	repetitive peak reverse voltage				1600		V	
I _{T(RMS)}	RMS on-state current	half sine wave			101		А	
I _{TSM}	non-repetitive peak on-	half sine wave; $T_{j(init)}$ = 25 °C; t_p = 10 ms		1500			Α	
	state current	half sine wave; $T_{j(init)}$ = 125 °C; t_p = 10 ms			1350		А	
		half sine wave; $T_{j(init)}$ = 25 °C; t_p = 8.3 ms		1650			Α	
		half sine wave; $T_{j(init)}$ = 125 °C; t_p = 8.3 ms			1485		А	
Symbol	Parameter	Conditions	Notes	Min	Тур	Max	Unit	
Static ch	aracteristics							
I _{GT}	gate trigger current	$V_D = 12 \text{ V}; I_T = 0.1 \text{ A}; T_j = 25 \text{ °C}$		30	-	100	mA	
V_{GT}	gate trigger voltage	$V_D = 12 \text{ V}; I_T = 0.1 \text{ A}; T_j = 25 \text{ °C}$		-	-	1.50	V	
V _T	on-state voltage	I _T = 200 A; T _j = 25 °C		-	-	1.70	V	

5. Pinning information

Table 2. Pinning information



6. Ordering information

Table 3. Ordering information

Type number	Package Name	Orderable part number	_		Package version	Package issue date
WAT100TBS16	WeEnTOP-B	WAT100TBS16T	EPE	30	WeEnTOP-BPAT-A	18-Apr-2024

7. Marking

Table 4. Marking codes

Type number	Marking codes
WAT100TBS16	WAT100TBS16

8. Limiting values

Table 5. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134).

Symbol	Parameter	Conditions	Notes	Values	Unit
V_{DRM}	repetitive peak forward voltage			1600	V
V_{RRM}	repetitive peak reverse voltage			1600	V
I _{T(RMS)}	RMS on-state current	half sine wave		101	Α
I _{TSM}	non-repetitive peak onstate	half sine wave; $T_{j(init)}$ = 25 °C; t_p = 10 ms		1500	А
	current	half sine wave; $T_{j(init)}$ = 125 °C; t_p = 10 ms		1350	А
		half sine wave; $T_{j(init)}$ = 25 °C; t_p = 8.3 ms		1650	Α
		half sine wave; $T_{j(init)}$ = 125 °C; t_p = 8.3 ms		1485	А
I ² t	I ² t for fusing	t _p = 10 ms; sine-wave pulse		11.25	kA ² s
dl _⊤ /dt	rate of rise of on-state current	I _G = 200 mA; T _j = 125 °C		200	A/µs
I _{GM}	peak gate current			10	А
V_{RGM}	peak reverse gate voltage			5	V
P_GM	peak gate power			20	W
$P_{G(AV)}$	average gate power	over any 20 ms period		0.5	W
T_{vj}	virtual junction temperature			-40 to 125	°C
T _{op}	operation temperature			-40 to 125	°C
T _{stg}	storage temperature			-40 to 125	°C

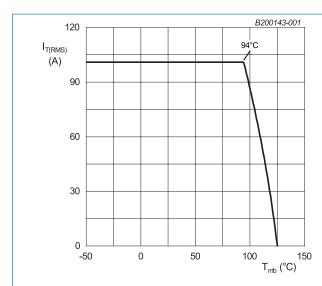
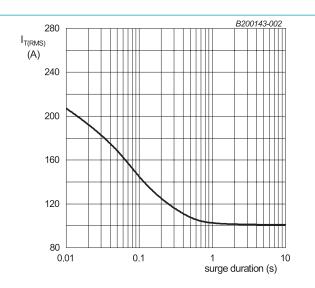


Fig. 1. RMS on-state current as a function of mounting base temperature; maximum values



 $f = 50 \text{ Hz}; T_{mb} = 94 \text{ }^{\circ}\text{C}$

Fig. 2. RMS on-state current as a function of surge duration; maximum values

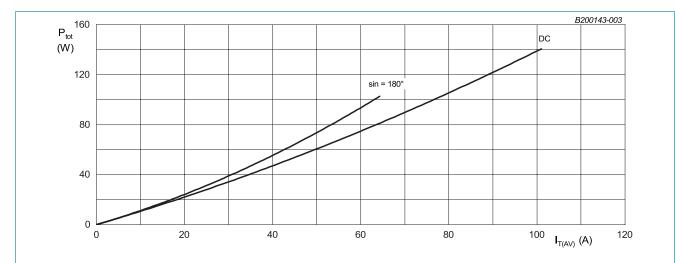
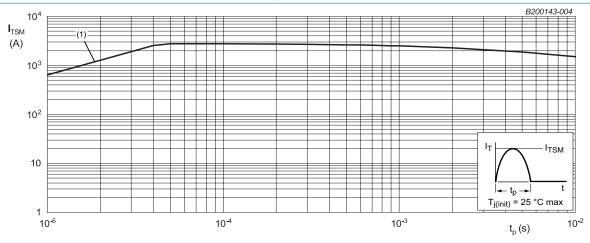


Fig. 3. Total power dissipation as a function of average on-state current; maximum values



 $t_p \le 10 \text{ ms}$ (1) $dI_T/dt \text{ limit}$

Fig. 4. Non-repetitive peak on-state current as a function of pulse width; maximum values

9. Thermal characteristics

Table 6. Thermal characteristics

Symbol	Parameter	Conditions	Notes	Min	Тур	Max	Unit
R _{th(j-c)}	thermal resistance from	per thyristor		-	-	0.6	K/W
	junction to case	per module		-	-	0.3	K/W

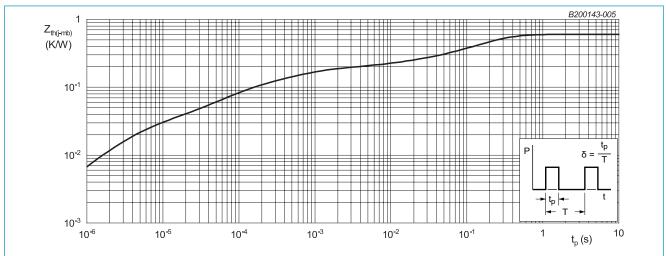


Fig. 5. Transient thermal impedance from junction to mounting base as a function of pulse duration; per thyristor

10. Package characteristics

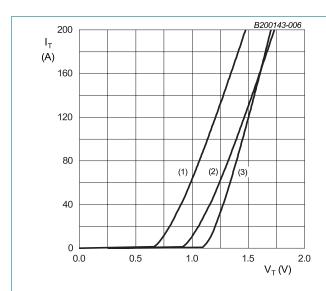
Table 7. Isolation characteristics

Symbol	Parameter	Conditions	Notes	Min	Тур	Max	Unit
V _{isol}	isolation voltage	50/60 Hz; RMS; $I_{ISOL} \le 1$ mA; t = 1 second; AC		-	-	3600	V
		50/60 Hz; RMS; I _{ISOL} ≤ 1 mA; t = 1 minute; AC		-	-	2500	V

11. Characteristics

Table 8. Characteristics

Symbol	Parameter	Conditions	Notes	Min	Тур	Max	Unit
Static ch	aracteristics			,			
I _{GT}	gate trigger current	V _D = 12 V; I _T = 0.1 A; T _j = 25 °C		30	-	100	mA
V_{GT}	gate trigger voltage	V _D = 12 V; I _T = 0.1 A; T _j = 25 °C		-	-	1.50	V
		$V_D = 2/3 V_{DRM}$; $I_T = 0.1 A$; $T_j = 125 °C$		0.25	-	-	V
I_{GD}	gate non-trigger current	T _j = 125 °C		-	-	8.5	mA
V_{GD}	gate non-trigger voltage	T _j = 125 °C		-	-	0.2	V
I _L	latching current	V _D = 12 V; I _T = 0.1 A; T _j = 25 °C		-	-	300	mA
I _H	holding current	V _D = 12 V; T _j = 25 °C		-	-	200	mA
V _T	on-state voltage	I _T = 200 A; T _j = 25 °C		-	-	1.70	V
V _{TO}	threshold voltage	T _j = 125 °C		-	-	1.0	V
r _T	slope resistance	T _j = 125 °C		-	-	3.5	mΩ
I _D	off-state current	V _D = 1600 V; T _j = 25 °C		-	-	100	μΑ
		V _D = 1600 V; T _j = 125 °C		-	-	15	mA
I _R	reverse current	V _R = 1600 V; T _j = 25 °C		-	-	100	μΑ
		V _R = 1600 V; T _j = 125 °C		-	-	15	mA
Dynamic	characteristics		1				
dV _D /dt	rate of rise of off-state voltage	V_{DM} = 1072 V; T_j = 125 °C; $(V_{DM}$ = 67% of V_{DRM}); exponential waveform; gate open circuit		1500	-	-	V/µs
t _{gt}	gate-controlled turn-on time	$I_{TM} = 40 \text{ A}; V_D = 800 \text{ V}; I_G = 100 \text{ mA};$ $(dI_G/dt)_M = 1 \text{ A/}\mu\text{s}; T_J = 25 \text{ °C}$		-	2	-	μs
t _q	commutated turn-off time	$I_{TM} = 2 \text{ A}; t_p = 50 \text{ µs}; dV/dt = 5 \text{ V/µs};$ $dI/dt = 30 \text{ A/µs}; T_i = 25 ^{\circ}\text{C}$		-	150	-	μs



 V_{TO} = 1.034 V; r_{T} = 0.0035 Ω

(1) T_j = 125 °C; typical values (2) T_i = 125 °C; maximum values

(3) T_i = 25 °C; maximum values

Fig. 6. On-state current as a function of on-state voltage

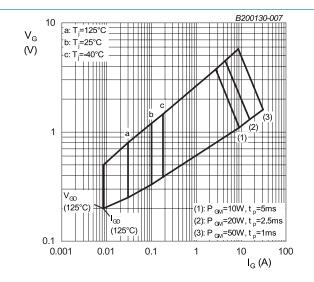
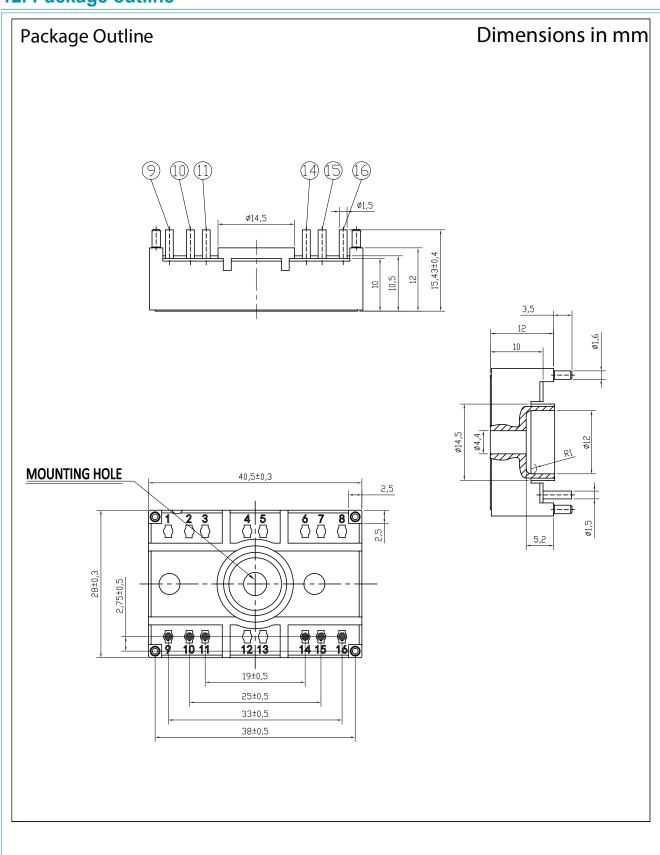


Fig. 7. Gate voltage as a function of gate current

12. Package outline



13. Legal information

Data sheet status

Document status [1][2]	Product status [3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
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WAT100TBS16

SCR Module

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